

(0.80 mm) .0315"

QTE SERIES

HIGH-SPEED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QTE

Insulator Material: Liquid Crystal Polymer Terminal Material: Phosphor Bronze Plating: Au or Sn over 50 μ" (1.27 μm) Ni Current Rating: Contact: 2 A per pin (2 pins powered) Ground Plane: 23 A per ground plane (1 ground plane powered) Operating Temp Range:
-55 °C to +125 °C
Voltage Rating:
225 VAC mated with QSE
8 5 mm Stack Height

Max Cycles: 100 RoHS Compliant: Yes

PROCESSING

Lead-Free Solderable: Yes SMT Lead Coplanarity: (0.10 mm) .004" max (020-060) Board Stacking:

For applications requiring more than two connectors per board contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



PROTOCOLS

- 100 GbE
- XAUI
- PCI Express®
- SATA
- MGT (Rocket I/O)
- InfiniBand™

ALSO AVAILABLE (MOQ Required)

- 15 mm, 22 mm and 30 mm stack height
- 30 μ" (0.76 μm) Gold (Specify -H plating for Data Rate cable mating applications.)
- Edge Mount, Guide Posts, Screw Down & Friction Lock
- 56 (-DP), 80, 100 positions per row
- Retention Option Contact Samtec.

Board Mates:

Cable Mates:

EQCD, EQDF (See Also Available Note)

Standoffs:

POWER/SIGNAL APPLICATION



Compatible with UMPT/UMPS for flexible two-piece power/signal solutions

Integral metal plane for power or ground Standard stack heights from 5 mm to 25 mm HIGH-SPEED CHANNEL PERFORMANCE EXTENDED LIFE PRODUCT QTE-D/QSE-D QTE-DP/QSF-DP

QTE-D/QSE-D or QTE-DP/QSE-DP @ 5 mm Mated Stack Height

Rating based on Samtec reference channel.For full SI performance data visit Samtec.comor contact SIG@samtec.com

PLATING

OPTION

OTHER

-020, -040, -060 (40 total pins per bank = -D)

PINS PER ROW

NO. OF PAIRS

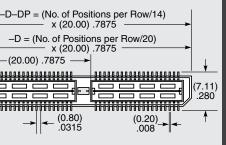
-014, -028, -042 (14 pairs per bank = -D-DP)

Specify **LEAD STYLE** from

LEAD

STYLE

chart







(5.97)



= Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

= 10 µ" (0.25 µm) Gold on Signal Pins and Ground Plane,

Matte Tin on tails = Electro-Polished

Selective 50 μ" (1.27 μm) min Au over 150μ" (3.81 μm) Ni on Signal Pins in contact area, 10 μ" (0.25 μm) min Au over 50 μ" (1.27 μm) Ni on Ground Plane in contact area. Matte Tin over 50µ" (1.27 µm) min Ni on all solder tails

*Note: -C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.

–D = Single-Ended -D-DP

Differential Pair (-01 only)

= (7.00 mm) .275" DIA Polyimide Film Pick & Place Pad

OPTION

-TR Tape & Reel Packaging (N/A -05 & -07

lead style)

= Latching Option (N/A on -042 &

060 positions)

QTE LEAD STYLE	A	HEIGHT WITH QSE*
-01	(4.27) .168	(5.00) .197
-02	(7.26) .286	(8.00) .315
-03	(10.27) .404	(11.00) .433
-04	(15.25) .600	(16.00) .630
-05	(18.26) .718	(19.00) .748
-07	(24.24) .954	(25.00) .984
-09	(13.26) .522	(14.00) .551

*Processing conditions will affect mated height. See SO Series for board space tolerances

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